

## **Product End-of-Life Disassembly Instructions**

Product Name / Model: Rugged Medical Tablet / 302MD

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of DT Research products to remove components and materials requiring selective treatment, as defined by EU Directive 2012/19/EU of the European Parliament and of the Council of 4 July 2012 on waste electrical and electronic equipment (WEEE).

## **1.0 Items Requiring Selective Treatment**

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards Assemblies (PCBA)	With a surface greater than 10 sq cm	1
Mass storage device	Permanently soldered to PCBA	0
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches,	0
LCD Display	a surface greater than 100 sq cm includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and	Include the cartridges, print heads, tubes, vent chambers, and service	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Size (if applicable)

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

- 1. Dismantle the handle, corners, I/O doors and back cover.
- 2. Dismantle buttons cover and side frame
- 3. Dismantle bottom cover, top cover and buckles
- 4. Remove battery pack
- 5. Dismantle back-up battery
- 6. Dismantle rear enclosure
- 7. Dismantle mother board
- 8. Dismantle I/O board
- 9. Dismantle the LCD display

3.2 Optional Graphic. Model 302MD is same as model DT302RP excluded enclosure color so that the disassembly process is same. Please refer to "DT302RP Product End-of-Life Disassembly Instructions"